ABSTRACT

An adhesive composition for forming an adhesive layer used in a laminate including a first body that is a semiconductor substrate or an electronic device layer, a second body that is a support substrate transmitting an infrared laser, and an adhesive layer provided between the first body and the second body, wherein after processing the first body, the adhesive layer is irradiated with the infrared laser from the second body side, and then the first body and the second body are separated,

the adhesive composition containing: an adhesive component having a siloxane bond, a release agent component, and an infrared-absorbing agent.

FIG. 1